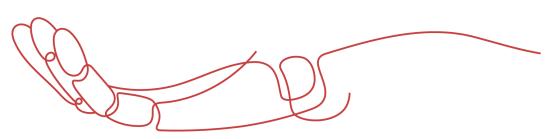


# PRODUCT DATA SHEET



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Datasheet

ces Sami

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.

**ESD Protection Diode Array** 

#### **Features**

- 400 Watts peak pulse power (tp =  $8/20\mu$ s)
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance ( $C_i$ =60 pF typ.)
- Protection two data lines:
- IEC 61000-4-2 ±30kV contact ±30kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 12A (8/20μs)



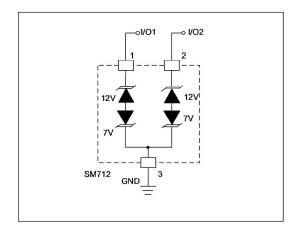
## **Applications**

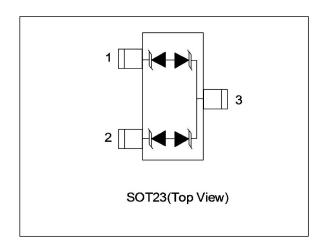
- Dataline
- Automatic Teller Machines
- Net works
- Power line

#### **Mechanical Data**

- SOT23 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

## **Schematic & PIN Configuration**







**Absolute Maximum Rating** 

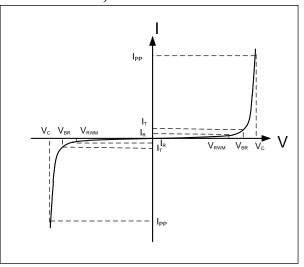
Rating	Symbol	Value	Units
Peak Pulse Power ( t <sub>p</sub> =8/20μs )	P <sub>PP</sub>	400	Watts
Peak Pulse Current ( t <sub>p</sub> =8/20μs ) (note1)	Pulse Current ( $t_p = 8/20 \mu s$ ) (note1) $I_{pp}$ 12		A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	30 30	kV
Lead Soldering Temperature	$T_{ m L}$	260(10seconds)	$^{\circ}$ C
Junction Temperature	$T_{ m J}$	-55 to + 125	$^{\circ}$ C
Storage Temperature	$T_{ m stg}$	-55 to + 125	$^{\circ}$ C

### **Electrical Characteristics**

			Pins 1 to 3 and 2 to 3 (12V TVS)		Pins 3 to 1 and 3 to 2 (7V TVS)				
Parameter	Symbol	Conditions	Min	Typical	Max	Min	Typical	Max	Units
Reverse Stand-Off Voltage	Vrwm				12			7	V
Reverse Breakdown Voltage	$V_{ ext{BR}}$	IT=1mA	13.3			7.5			V
Reverse Leakage Current	Ir	VR=V <sub>RWM</sub>			1			1	μΑ
Clamping Voltage	Vc	IPP=12A,tp=8/20μs			20			10	V
Junction Capacitance	Cj	$V_R = 0V$ , $f = 1MHz$		60	75		60	75	pF

# Electrical Parameters (TA = $25 \, ^{\circ}$ C unless otherwise noted)

Symbol	Parameter		
$\mathbf{I}_{ ext{PP}}$	Maximum Reverse Peak Pulse Current		
Vc	Clamping Voltage @ Ipp		
V <sub>RWM</sub>	Working Peak Reverse Voltage		
IR	Maximum Reverse Leakage Current @ VRWM		
$V_{\text{BR}}$	Breakdown Voltage @ IT		
Iτ	Test Current		



Note:.  $8/20\mu s$  pulse waveform.



### **Typical Characteristics**

Figure 1: Peak Pulse Power vs. Pulse Time

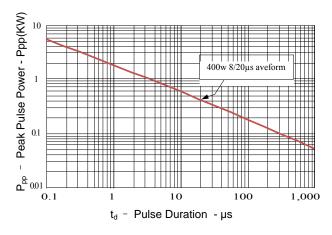


Figure 2: Power Derating Curve

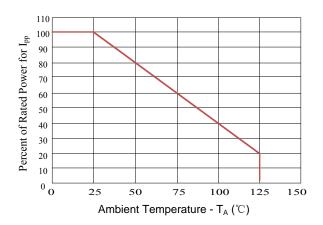


Figure3: Pulse Waveform

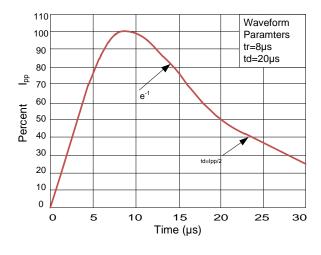
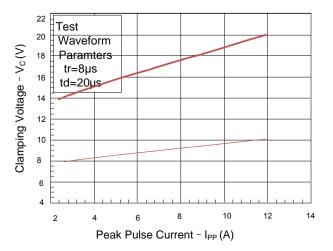
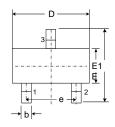


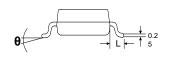
Figure 4: Clamping Voltage vs.lpp

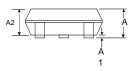




## **Outline Drawing – SOT23**







	1			
	DIMENS			
	MILLIMETER		INCHES	
SYMBOL	MIN	MAX	MIN	MAX
А	0.89	1.12	0.035	0.044
A1	0.01	0.10	0.0006	0.0043
A2	0.88	1.02	0.035	0.040
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.082	0.104
E1	1.20	1.40	0.047	0.055
е	1.90BSC		0.75 BSC	
L	0.40	0.60	0.015	0.024
θ	0	8.	0	8.



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